REMARKS

Claims 1-13 are pending in the above-identified patent application. Favorable consideration of the amendment and allowance of the claims is respectfully requested.

Applicant wishes to thank Examiner Nguyen for the withdrawal of the finality of the last Official Action.

There is an objection to the Title of this application and Claims 6, 10 and 13. Applicant has amended the Title and Claims 6 and 10. Support for the amendment to Claim 10 may be found at page 14. Support for the means for coupling the main body with a transport mechanism in Claim 13 may be found at page 12, line 8 through page 13, line 8. This part of the specification discusses, inter alia, features of a leadframe carrier coupler assembly 80. Withdrawal of the objections is earnestly solicited.

Before addressing the subject matter of the claims, a discussion of Applicant's disclosure is provided. The disclosure is directed to a variety of features relating to the testing of semiconductor devices. One aspect of this disclosure is a carrier for a leadframe containing non-singulated semiconductor devices. This carrier provides support for the leadframe during a test. In one embodiment illustrated in FIG. 2, a carrier 2 has a main body 20 and a leadframe support member 21 provided with a plurality of grooves 22. These grooves 22 are sized to receive semiconductor devices with the leadframe being supported by the carrier 2. See page 9, lines 3-21. FIG. 16 illustrates the support provided for the leads of semiconductor devices 90 by the leadframe support member 21 when a test operation is performed. Semiconductor devices 90 are received within the grooves with the leads of the

semiconductor devices 90 being supported by a surface of the leadframe support member 21. When the devices undergo testing, test probes engage the leads and exert a downward pressure as indicated by the downward arrows shown in FIG. 16. This downward pressure is supported by the leadframe support member 21 as illustrated by the upward arrows shown in FIG. 16. See page 13, lines 9-21.

Claim 1 stands rejected as anticipated by Jeong. According to the Official Action, Jeong shows a main body (40), a lead frame support member (20) with at least one groove (22) for receiving semiconductor devices (1) such that in use leads extending from the semiconductor devices lie on a surface of the support member (20).

Jeong discloses a leadframe 10 that is placed on a holding plate 20. The leadframe 10 has a plurality of chips with leads 12. The holding plate 20 is formed with windows 22. Positioned below the leadframe 10 is a substrate 30 having a securing layer 32 and probes 33. See FIG. 1. The leads 12 and chips 1 are exposed through the windows 22 of the holding plate 20. See col. 4, lines 21-27. In particular, these windows 22 are made larger than the securing layer 32 so that the probes 33 contact leads 12 within window 22 when the leadframe 10 moves downward. See col. 5, lines 44-48 and FIGS. 4A and 4B.

Claim 1 is directed to an apparatus for supporting during a testing operation a leadframe formed with at least one row of non-singulated semiconductor devices. The apparatus includes a main body and a leadframe support member, wherein the leadframe support member is formed with at least one groove for receiving the semiconductor devices such that in use leads extending from the devices lie on a

surface of the support member. Claim 1 is not anticipated by Jeong for at least two reasons.

Jeong does not show a leadframe support member formed with at least one groove for receiving the semiconductor devices. Jeong forms windows 22 in the holding plate 10, not grooves. And there is nothing set forth in the Official Action or in Jeong to support the view that a "groove" reads-on Jeong's window. A "groove" is a channel or depression, which does not include Jeong's window 22. For at least this reason, Claim 1 is not anticipated by Jeong.

Jeong also does not disclose a groove for receiving the semiconductor devices such that in use leads extending from the devices lie on a surface of the support member. As best understood, the Official Action has concluded that Jeong's leads (12) lie on a surface of the support member (20). Applicant disagrees. Jeong states that the leads 12 and chips 1 are exposed through the windows 22 of the holding plate 20 and the probes 33 contact leads 12 within window 22. See col. 4, lines 21-27; col. 5, lines 44-48 and FIGS. 4A and 4B. Accordingly, as the leads 12 are located within the windows 22 and thus do not lie on the support plate 20, a finding that Jeong's leads 12 lie on the support plate 20 is simply untenable. The leadframe 10 may lie on the support plate 20, but the leads 12 do not. Accordingly, for this additional reason Claim 1 is not anticipated by Jeong.

For at least these reasons, Applicant respectfully requests that the rejection of Claim 1 be withdrawn and this claim allowed.

Claims 2-13 are dependent on Claim 1 and recite additional features that further distinguish over the prior art. Due to their dependence on an allowable claim, it is not necessary at this point to discuss the features in Claims 2-13 that further

distinguish over the prior art. Withdrawal of the rejections of Claims 2-13 and allowance of these claims is earnestly solicited.

Should any questions arise in connection with this application or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application the undersigned respectfully requests that he be contacted at the number indicated below.

Respectfully submitted,

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